Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	225400
Number of Logic Elements/Cells	597000
Total RAM Bits	53248000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-FBGA (40x40)
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxeb6r3f40c2n

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed Grade	Core Speed Grade							
	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L	I3YY	I4
3 GX channel—8.5 Gbps	—	Yes	Yes	Yes	—	Yes	Yes (4)	Yes

Notes to Table 1:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

(3) C2L, I2L, and I3L speed grades are for low-power devices.

(4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transceiver Speed Grade	Core Speed Grade			
	C1	C2	I2	I3
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	—	—
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes

Notes to Table 2:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.

CAUTION Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V_{CC}	Power supply for core voltage and periphery circuitry	–0.5	1.35	V
V_{CCPT}	Power supply for programmable power technology	–0.5	1.8	V
V_{CCPGM}	Power supply for configuration pins	–0.5	3.9	V
V_{CC_AUX}	Auxiliary supply for the programmable power technology	–0.5	3.4	V
V_{CCBAT}	Battery back-up power supply for design security volatile key register	–0.5	3.9	V
V_{CCPD}	I/O pre-driver power supply	–0.5	3.9	V
V_{CCIO}	I/O power supply	–0.5	3.9	V

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V_{CCD_FPLL}	PLL digital power supply	–0.5	1.8	V
V_{CCA_FPLL}	PLL analog power supply	–0.5	3.4	V
V_I	DC input voltage	–0.5	3.8	V
T_J	Operating junction temperature	–55	125	°C
T_{STG}	Storage temperature (No bias)	–65	150	°C
I_{OUT}	DC output current per pin	–25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V_{CCA_GXBL}	Transceiver channel PLL power supply (left side)	GX, GS, GT	–0.5	3.75	V
V_{CCA_GXBR}	Transceiver channel PLL power supply (right side)	GX, GS	–0.5	3.75	V
V_{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	–0.5	3.75	V
V_{CCHIP_L}	Transceiver hard IP power supply (left side)	GX, GS, GT	–0.5	1.35	V
V_{CCHIP_R}	Transceiver hard IP power supply (right side)	GX, GS, GT	–0.5	1.35	V
V_{CCHSSI_L}	Transceiver PCS power supply (left side)	GX, GS, GT	–0.5	1.35	V
V_{CCHSSI_R}	Transceiver PCS power supply (right side)	GX, GS, GT	–0.5	1.35	V
V_{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	–0.5	1.35	V
V_{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	–0.5	1.35	V
V_{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	–0.5	1.35	V
V_{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	–0.5	1.35	V
V_{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	–0.5	1.35	V
V_{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	–0.5	1.35	V
V_{CCL_GTBR}	Transmitter clock network power supply (right side)	GT	–0.5	1.35	V
V_{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	–0.5	1.8	V
V_{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	–0.5	1.8	V

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to –2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum (4)	Typical	Maximum (4)	Unit
V_{CCR_GXBR} (2)	Receiver analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
V_{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCT_GXBL} (2)	Transmitter analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
V_{CCT_GXBR} (2)	Transmitter analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
V_{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V_{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V_{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Notes to Table 7:

(1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

(2) Refer to Table 8 to select the correct power supply level for your design.

(3) When using ATX PLLs, the supply must be 3.0 V.

(4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 2 of 2)

Symbol	Description	Conditions	Calibration Accuracy				Unit
			C1	C2,I2	C3,I3, I3YY	C4,I4	
50-Ω R_S	Internal series termination with calibration (50-Ω setting)	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
34-Ω and 40-Ω R_S	Internal series termination with calibration (34-Ω and 40-Ω setting)	V_{CCIO} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R_S	Internal series termination with calibration (48-Ω, 60-Ω, 80-Ω, and 240-Ω setting)	V_{CCIO} = 1.2 V	±15	±15	±15	±15	%
50-Ω R_T	Internal parallel termination with calibration (50-Ω setting)	V_{CCIO} = 2.5, 1.8, 1.5, 1.2 V	–10 to +40	–10 to +40	–10 to +40	–10 to +40	%
20-Ω, 30-Ω, 40-Ω ,60-Ω, and 120-Ω R_T	Internal parallel termination with calibration (20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω setting)	V_{CCIO} = 1.5, 1.35, 1.25 V	–10 to +40	–10 to +40	–10 to +40	–10 to +40	%
60-Ω and 120-Ω R_T	Internal parallel termination with calibration (60-Ω and 120-Ω setting)	V_{CCIO} = 1.2	–10 to +40	–10 to +40	–10 to +40	–10 to +40	%
25-Ω $R_{S\_left\_shift}$	Internal left shift series termination with calibration (25-Ω $R_{S\_left\_shift}$ setting)	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Note to Table 11:

(1) OCT calibration accuracy is valid at the time of calibration only.

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)

Symbol	Description	Conditions	Resistance Tolerance				Unit
			C1	C2,I2	C3, I3, I3YY	C4, I4	
25-Ω R, 50-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 3.0 and 2.5 V	±30	±30	±40	±40	%
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 1.8 and 1.5 V	±30	±30	±40	±40	%
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 1.2 V	±35	±35	±50	±50	%

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) *(1)*

Symbol	Description	V_{CCIO} (V)	Typical	Unit
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	%/°C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.2	0.317	

Note to Table 13:

(1) Valid for a V_{CCIO} range of ±5% and a temperature range of 0° to 85°C.

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C_{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C_{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C_{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
$I_{IOPIN (DC)}$	DC current per I/O pin	300 μA
$I_{IOPIN (AC)}$	AC current per I/O pin	8 mA *(1)*
$I_{XCVR-TX (DC)}$	DC current per transceiver transmitter pin	100 mA
$I_{XCVR-RX (DC)}$	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}|$ = C dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.

You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications *(1)*

Clock Network	ATX PLL			CMU PLL *(2)*			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 *(3)*	14.1	—	6	12.5	—	6	3.125	—	3
x6 *(3)*	—	14.1	6	—	12.5	6	—	3.125	6
x6 PLL Feedback *(4)*	—	14.1	Side-wide	—	12.5	Side-wide	—	—	—
xN (PCIe)	—	8.0	8	—	5.0	8	—	—	—
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above and below PLL	3.125	3.125	Up to 13 channels above and below PLL
	—	8.01 to 9.8304	Up to 7 channels above and below PLL						

Notes to Table 24:

(1) Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

(2) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

(3) Channel span is within a transceiver bank.

(4) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5) *(1)*

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Transmitter REFCLK Phase Noise (622 MHz) *(18)*	100 Hz	—	—	-70	—	—	-70	dBc/Hz
	1 kHz	—	—	-90	—	—	-90	
	10 kHz	—	—	-100	—	—	-100	
	100 kHz	—	—	-110	—	—	-110	
	≥ 1 MHz	—	—	-120	—	—	-120	
Transmitter REFCLK Phase Jitter (100 MHz) *(15)*	10 kHz to 1.5 MHz (PCIe)	—	—	3	—	—	3	ps (rms)
RREF *(17)*	—	—	1800 ± 1%	—	—	1800 ± 1%	—	Ω
Transceiver Clocks								
`fixedclk` clock frequency	PCIe Receiver Detect	—	100 or 125	—	—	100 or 125	—	MHz
Reconfiguration clock (`mgmt_clk_clk`) frequency	—	100	—	125	100	—	125	MHz
Receiver								
Supported I/O Standards	—	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS						
Data rate (Standard PCS) *(21)*	GX channels	600	—	8500	600	—	8500	Mbps
Data rate (10G PCS) *(21)*	GX channels	600	—	12,500	600	—	12,500	Mbps
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Absolute V_{MAX} for a receiver pin *(3)*	GT channels	—	—	1.2	—	—	1.2	V
Absolute V_{MIN} for a receiver pin	GT channels	–0.4	—	—	–0.4	—	—	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) before device configuration *(20)*	GT channels	—	—	1.6	—	—	1.6	V
	GX channels	*(8)*						
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device configuration *(16)*, *(20)*	GT channels V_{CCR_GTB} = 1.05 V (V_{ICM} = 0.65 V)	—	—	2.2	—	—	2.2	V
	GX channels	*(8)*						
Minimum differential eye opening at receiver serial input pins *(4)*, *(20)*	GT channels	200	—	—	200	—	—	mV
	GX channels	*(8)*						

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5) *(1)*

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Differential on-chip termination resistors *(7)*	GT channels	—	100	—	—	100	—	Ω
Differential on-chip termination resistors for GX channels *(19)*	85-Ω setting	—	85 ± 30%	—	—	85 ± 30%	—	Ω
	100-Ω setting	—	100 ± 30%	—	—	100 ± 30%	—	Ω
	120-Ω setting	—	120 ± 30%	—	—	120 ± 30%	—	Ω
	150-Ω setting	—	150 ± 30%	—	—	150 ± 30%	—	Ω
V_{ICM} (AC coupled)	GT channels	—	650	—	—	650	—	mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 0.85 V or 0.9 V	—	600	—	—	600	—	mV
	VCCR_GXB = 1.0 V full bandwidth	—	700	—	—	700	—	mV
	VCCR_GXB = 1.0 V half bandwidth	—	750	—	—	750	—	mV
t_{LTR} *(9)*	—	—	—	10	—	—	10	µs
t_{LTD} *(10)*	—	4	—	—	4	—	—	µs
t_{LTD_manual} *(11)*	—	4	—	—	4	—	—	µs
$t_{LTR\_LTD\_manual}$ *(12)*	—	15	—	—	15	—	—	µs
Run Length	GT channels	—	—	72	—	—	72	CID
	GX channels	*(8)*						
CDR PPM	GT channels	—	—	1000	—	—	1000	± PPM
	GX channels	*(8)*						
Programmable equalization (AC Gain) *(5)*	GT channels	—	—	14	—	—	14	dB
	GX channels	*(8)*						
Programmable DC gain *(6)*	GT channels	—	—	7.5	—	—	7.5	dB
	GX channels	*(8)*						
Differential on-chip termination resistors *(7)*	GT channels	—	100	—	—	100	—	Ω
Transmitter								
Supported I/O Standards	—	1.4-V and 1.5-V PCML						
Data rate (Standard PCS)	GX channels	600	—	8500	600	—	8500	Mbps
Data rate (10G PCS)	GX channels	600	—	12,500	600	—	12,500	Mbps

Figure 6 shows the Stratix V DC gain curves for GT channels.

Figure 6. DC Gain Curves for GT Channels

Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Symbol	Parameter	Min	Typ	Max	Unit
t_{INCCJ} (3), (4)	Input clock cycle-to-cycle jitter ($f_{REF} \geq 100$ MHz)	—	—	0.15	UI (p-p)
	Input clock cycle-to-cycle jitter ($f_{REF} < 100$ MHz)	–750	—	+750	ps (p-p)
t_{OUTPJ_DC} (5)	Period Jitter for dedicated clock output ($f_{OUT} \geq$ 100 MHz)	—	—	175 (1)	ps (p-p)
	Period Jitter for dedicated clock output ($f_{OUT} <$ 100 MHz)	—	—	17.5 (1)	mUI (p-p)
t_{FOUTPJ_DC} (5)	Period Jitter for dedicated clock output in fractional PLL ($f_{OUT} \geq 100$ MHz)	—	—	250 (11), 175 (12)	ps (p-p)
	Period Jitter for dedicated clock output in fractional PLL ($f_{OUT} < 100$ MHz)	—	—	25 (11), 17.5 (12)	mUI (p-p)
t_{OUTCCJ_DC} (5)	Cycle-to-Cycle Jitter for a dedicated clock output ($f_{OUT} \geq 100$ MHz)	—	—	175	ps (p-p)
	Cycle-to-Cycle Jitter for a dedicated clock output ($f_{OUT} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{FOUTCCJ\_DC}$ (5)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{OUT} \geq 100$ MHz)	—	—	250 (11), 175 (12)	ps (p-p)
	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{OUT} < 100$ MHz)+	—	—	25 (11), 17.5 (12)	mUI (p-p)
t_{OUTPJ_IO} (5), (8)	Period Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for a clock output on a regular I/O ($f_{OUT} < 100$ MHz)	—	—	60	mUI (p-p)
t_{FOUTPJ_IO} (5), (8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \geq 100$ MHz)	—	—	600 (10)	ps (p-p)
	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} < 100$ MHz)	—	—	60 (10)	mUI (p-p)
t_{OUTCCJ_IO} (5), (8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} < 100$ MHz)	—	—	60 (10)	mUI (p-p)
$t_{FOUTCCJ\_IO}$ (5), (8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \geq 100$ MHz)	—	—	600 (10)	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{CASC\_OUTPJ\_DC}$ (5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs ($f_{OUT} \geq 100$ MHz)	—	—	175	ps (p-p)
	Period Jitter for a dedicated clock output in cascaded PLLs ($f_{OUT} < 100$ MHz)	—	—	17.5	mUI (p-p)
f_{DRIFT}	Frequency drift after PFDENA is disabled for a duration of 100 µs	—	—	±10	%
dK_{BIT}	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k_{VALUE}	Numerator of Fraction	128	8388608	2147483648	—

Table 31. PLL Specifications for Stratix V Devices (Part 3 of 3)

Symbol	Parameter	Min	Typ	Max	Unit
f_{RES}	Resolution of VCO frequency (f_{INPFD} = 100 MHz)	390625	5.96	0.023	Hz

Notes to Table 31:

(1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(2) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.

(3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.

(4) f_{REF} is fIN/N when N = 1.

(5) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.99999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 44 on page 52.

(6) The cascaded PLL specification is only applicable with the following condition:
a. Upstream PLL: 0.59Mhz ≤ Upstream PLL BW < 1 MHz
b. Downstream PLL: Downstream PLL BW > 2 MHz

(7) High bandwidth PLL settings are not supported in external feedback mode.

(8) The external memory interface clock output jitter specifications use a different measurement method, which is available in Table 42 on page 50.

(9) The VCO frequency reported by the Quartus II software in the PLL Usage Summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.

(10) This specification only covers fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05 - 0.95 must be ≥ 1000 MHz, while f_{VCO} for fractional value range 0.20 - 0.80 must be ≥ 1200 MHz.

(11) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05-0.95 must be ≥ 1000 MHz.

(12) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20-0.80 must be ≥ 1200 MHz.

DSP Block Specifications

Table 32 lists the Stratix V DSP block performance specifications.

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 1 of 2)

Mode	Peformance							Unit
	C1	C2, C2L	I2, I2L	C3	I3, I3L, I3YY	C4	I4	
Modes using one DSP								
Three 9 x 9	600	600	600	480	480	420	420	MHz
One 18 x 18	600	600	600	480	480	420	400	MHz
Two partial 18 x 18 (or 16 x 16)	600	600	600	480	480	420	400	MHz
One 27 x 27	500	500	500	400	400	350	350	MHz
One 36 x 18	500	500	500	400	400	350	350	MHz
One sum of two 18 x 18(One sum of 2 16 x 16)	500	500	500	400	400	350	350	MHz
One sum of square	500	500	500	400	400	350	350	MHz
One 18 x 18 plus 36 (a x b) + c	500	500	500	400	400	350	350	MHz
Modes using two DSPs								
Three 18 x 18	500	500	500	400	400	350	350	MHz
One sum of four 18 x 18	475	475	475	380	380	300	300	MHz
One sum of two 27 x 27	465	465	450	380	380	300	290	MHz
One sum of two 36 x 18	475	475	475	380	380	300	300	MHz
One complex 18 x 18	500	500	500	400	400	350	350	MHz
One 36 x 36	475	475	475	380	380	300	300	MHz

Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.

☞ The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

Table 36 lists high-speed I/O timing for Stratix V devices.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 1 of 4)

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4,I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{HSCLK_in} (input clock frequency) True Differential I/O Standards	Clock boost factor W = 1 to 40 (4)	5	—	800	5	—	800	5	—	625	5	—	525	MHz
f_{HSCLK_in} (input clock frequency) Single Ended I/O Standards (3)	Clock boost factor W = 1 to 40 (4)	5	—	800	5	—	800	5	—	625	5	—	525	MHz
f_{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 (4)	5	—	520	5	—	520	5	—	420	5	—	420	MHz
f_{HSCLK_OUT} (output clock frequency)	—	5	—	800	5	—	800	5	—	625 (5)	5	—	525 (5)	MHz

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled

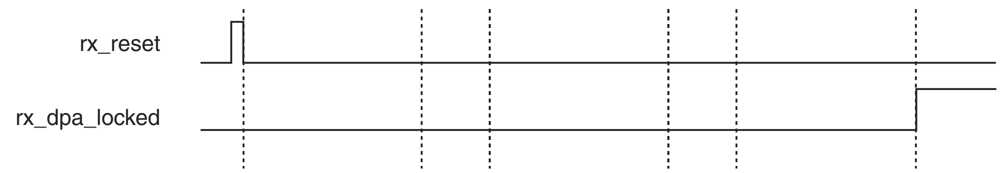


Table 37 lists the DPA lock time specifications for Stratix V devices.

Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only *(1), (2), (3)*

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions *(4)*	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

Notes to Table 37:

(1) The DPA lock time is for one channel.
(2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
(3) The DPA lock time stated in this table applies to both commercial and industrial grade.
(4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the **LVDS** soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate ≥ 1.25 Gbps. Table 38 lists the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate ≥ 1.25 Gbps.

Figure 8. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate ≥ 1.25 Gbps

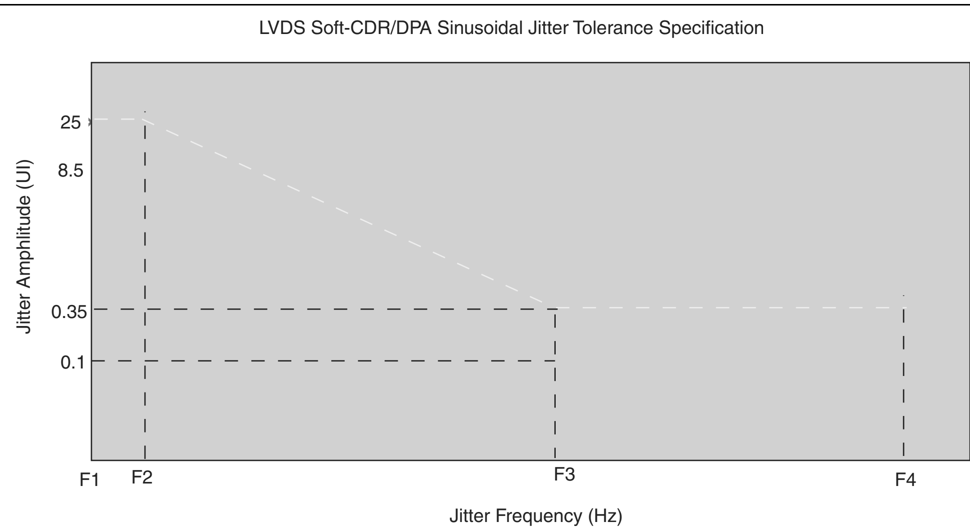


Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	µs
t_{STATUS}	nSTATUS low pulse width	268	1,506 (2)	µs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 (3)	µs
t_{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	—	µs
t_{ST2CK} (6)	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP ×8/×16)	—	125	MHz
	DCLK frequency (FPP ×32)	—	100	MHz
t_{CD2UM}	CONF_DONE high to user mode (4)	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period) (5)	—	—

Notes to Table 50:

(1) Use these timing parameters when the decompression and design security features are disabled.

(2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(3) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

(4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

(5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

(6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is more than 1.

Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52. DCLK Frequency Specification in the AS Configuration Scheme *(1), (2)*

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

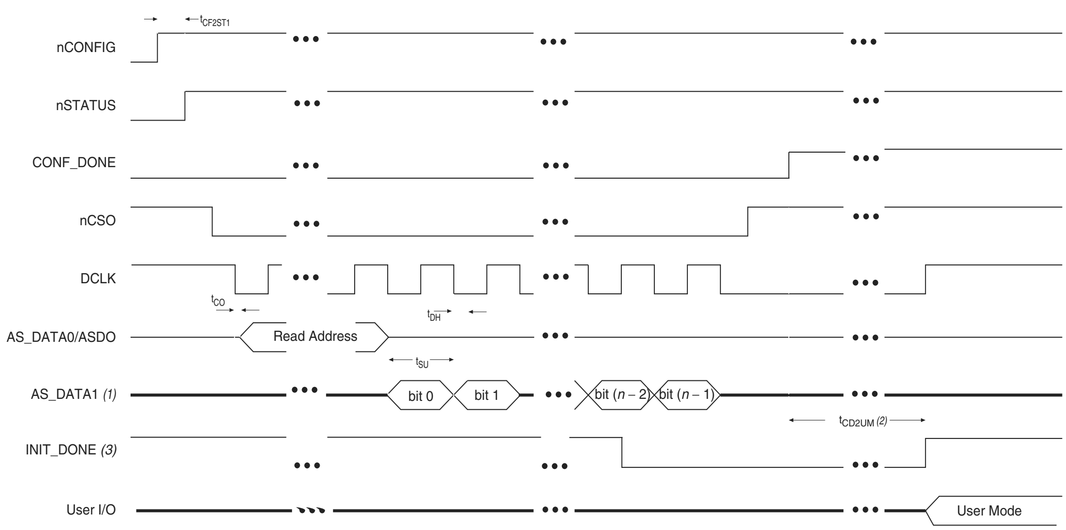
Notes to Table 52:

(1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.

(2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

Figure 14. AS Configuration Timing



Notes to Figure 14:

(1) If you are using AS ×4 mode, this signal represents the AS_DATA[3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.

(2) The initialization clock can be from internal oscillator or CLKUSR pin.

(3) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 53 lists the timing parameters for AS ×1 and AS ×4 configurations in Stratix V devices.

Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices *(1), (2)* **(Part 1 of 2)**

Symbol	Parameter	Minimum	Maximum	Units
t_{CO}	DCLK falling edge to AS_DATA0/ASDO output	—	2	ns
t_{SU}	Data setup time before falling edge on DCLK	1.5	—	ns
t_H	Data hold time after falling edge on DCLK	0	—	ns

Table 60. Glossary (Part 2 of 4)

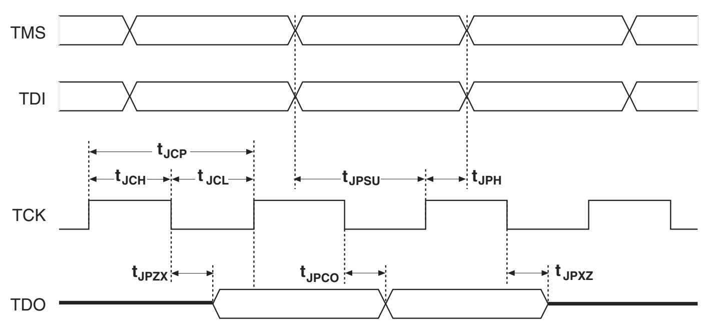
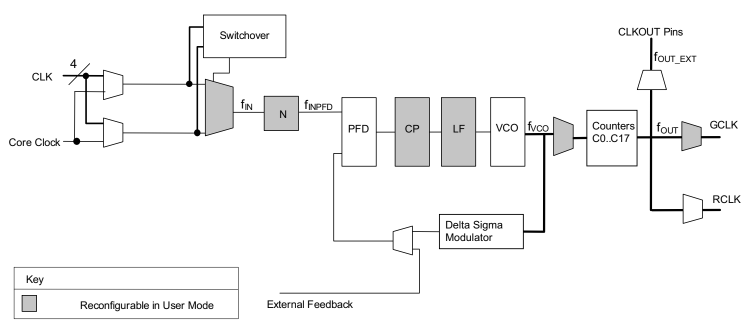
Letter	Subject	Definitions
G H I	—	—
J	J	High-speed I/O block—Deserialization factor (width of parallel data bus).
	JTAG Timing Specifications	JTAG Timing Specifications: 
K L M N O	—	—
P	**PLL Specifications**	**Diagram of PLL Specifications** *(1)*  **Note:** (1) `Core Clock` can only be fed by dedicated clock input pins or PLL outputs.
Q	—	—
R	$\mathbf{R}_L$	Receiver differential input discrete resistor (external to the Stratix V device).

Table 60. Glossary (Part 3 of 4)

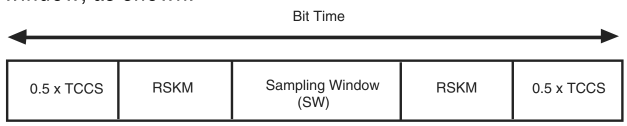
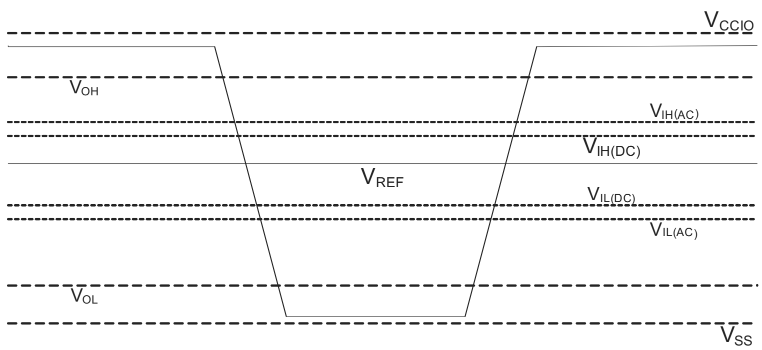
Letter	Subject	Definitions
S	**SW (sampling window)**	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown: 
	Single-ended voltage referenced I/O standard	The JEDEC standard for **SSTL** and **HSTL** I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing: *Single-Ended Voltage Referenced I/O Standard* 
T	t_C	High-speed receiver and transmitter input and output clock period.
	TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the *Timing Diagram* figure under **SW** in this table).
	t_{DUTY}	High-speed I/O block—Duty cycle on the high-speed transmitter output clock. **Timing Unit Interval (TUI)** The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = 1/(receiver input clock frequency multiplication factor) = t_C/w)
	t_{FALL}	Signal high-to-low transition time (80-20%)
	t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
	t_{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
	t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
	t_{RISE}	Signal low-to-high transition time (20-80%)
U	—	—

Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes
November 2014	3.3	■ Added the I3YY speed grade and changed the data rates for the GX channel in Table 1. ■ Added the I3YY speed grade to the V_{CC} description in Table 6. ■ Added the I3YY speed grade to V_{CCHIP_L}, V_{CCHIP_R}, V_{CCHSSI_L}, and V_{CCHSSI_R} descriptions in Table 7. ■ Added 240-Ω to Table 11. ■ Changed CDR PPM tolerance in Table 23. ■ Added additional max data rate for fPLL in Table 23. ■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25. ■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26. ■ Changed CDR PPM tolerance in Table 28. ■ Added additional max data rate for fPLL in Table 28. ■ Changed the mode descriptions for MLAB and M20K in Table 33. ■ Changed the Max value of f_{HSCLK_OUT} for the C2, C2L, I2, I2L speed grades in Table 36. ■ Changed the frequency ranges for C1 and C2 in Table 39. ■ Changed the **.rbf** file sizes for 5SGSD6 and 5SGSD8 in Table 47. ■ Added note about `nSTATUS` to Table 50, Table 51, Table 54. ■ Changed the available settings in Table 58. ■ Changed the note in “Periphery Performance”. ■ Updated the “I/O Standard Specifications” section. ■ Updated the “Raw Binary File Size” section. ■ Updated the receiver voltage input range in Table 22. ■ Updated the max frequency for the LVDS clock network in Table 36. ■ Updated the `DCLK` note to Figure 11. ■ Updated Table 23 VO_{CM} (DC Coupled) condition. ■ Updated Table 6 and Table 7. ■ Added the `DCLK` specification to Table 55. ■ Updated the notes for Table 47. ■ Updated the list of parameters for Table 56.
November 2013	3.2	■ Updated Table 28
November 2013	3.1	■ Updated Table 33
November 2013	3.0	■ Updated Table 23 and Table 28
October 2013	2.9	■ Updated the “Transceiver Characterization” section
October 2013	2.8	■ Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59 ■ Added Figure 1 and Figure 3 ■ Added the “Transceiver Characterization” section ■ Removed all “Preliminary” designations.